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## GaN 100W,0.8-2GHz ,28V,RF Power Transistor Description

The GTAH21140B4 is a 28V 100W CW device, both input and output matched GaN HEMT, ideal for multiple applications from 0.8-2GHz, and at higher voltage 32V, capable to output more than 120W.

It can support linear and saturated , pulsed or CW application, configured as push pull or single ended  $\frac{1}{2}$ 

There is no guarantee of performance when this part is used outside of stated frequencies.

Typical performance across 1-2GHz class AB application circuit with device soldered

#### CW signal,Idq=120mA

Voltage (V)	Freq (GHz)	Psat (W)	Eff (%)	Power Gain (dB)
28	0.8-2	110-135	>47	11-15
32	0.8-2	130-160	>46	12-16

# GTAH21140B4

#### **Applications**

- L band pulse power amplifier
- · wideband power amplifier
- · Beidou power amplifier

#### **Important Note: Proper Biasing Sequence for GaN HEMT Transistors**

#### **Turning the device ON**

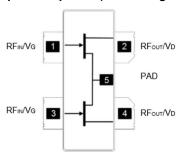
- 1. Set VGS to the pinch--off (VP) voltage, typically -5 V
- 2. Turn on VDS to nominal supply voltage
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

#### Turning the device OFF

- 1. Turn RF power off
- 2. Reduce VGS down to VP, typically -5 V
- 3. Reduce VDS down to 0 V
- 4. Turn off VGS

Figure 1: Pin Connection definition

#### Transparent top view (Backside grounding for source)



**Table 1. Maximum Ratings** 

Rating	Symbol	Value	Unit
DrainSource Voltage	V <sub>DSS</sub>	+150	Vdc
GateSource Voltage	V <sub>GS</sub>	-10 to +2	Vdc
Operating Voltage	V <sub>DD</sub>	36	Vdc
Maximum gate current	lgs	36	mA
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	T <sub>c</sub>	+150	°C
Operating Junction Temperature	TJ	+225	°C



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**Table 2. Thermal Characteristics** 

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case by FEA	Rejc	0.9	°C /W
T <sub>C</sub> = 85°C, at Pout=100W CW at 2GHz	K#JC	0.9	-C /VV

Table 3. Electrical Characteristics (TA = 25℃ unless otherwise noted)

#### DC Characteristics (measured on wafer prior to packaging)

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	VGS=-8V; IDS=36mA	V <sub>DSS</sub>		150		V
Gate Threshold Voltage	VDS =10V, ID = 36mA	$V_{GS(th)}$	-4		-2	V
Gate Quiescent Voltage	VDS =28V, IDS=180mA, Measured in Functional Test	$V_{GS(Q)}$		-2.4		V

#### **Ruggedness Characteristics**

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Load mismatch capability	2GHz, Pout=100W Pulsed CW					
	All phase,	VSWR		10:1		
	No device damages					

Figure 2: Median Lifetime vs. Channel Temperature

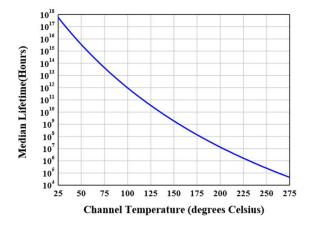
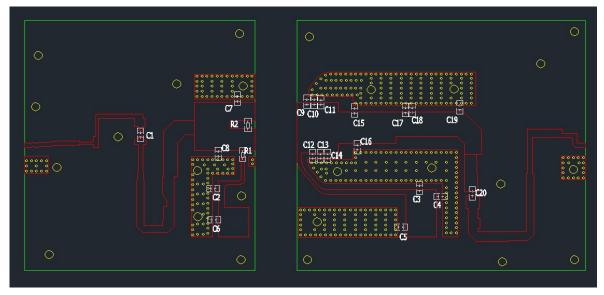


Figure 3: Picture of application board 1-2GHz class AB



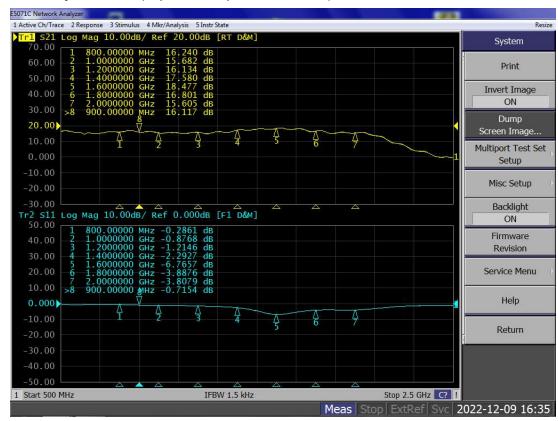


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Table 4. Bill of materials of application board (PCB layout upon request)

Component	Description	Suggestion	
C1,C2,C3,C4,C20	20pF	10uF/50V	
C5,C6	10uF	MQ101111	
C7,C8	3pF	MQ101111	
C9,C11,C17,C14	1pF	MQ101111	
C13,C19	0.5pF	MQ101111	
C10	1.8pF	MQ101111	
C12	0.8pF	MQ101111	
C15	1.2pF	MQ101111	
C16	2pF	MQ101111	
C18	1.5pF	MQ101111	
R1,R2	Chip Resistor,10 ohm	1206	
PCB	20Mil RO4350B		

Figure 4: Network analyzer S11/S21 (Idq=450mA, Input Power =0dBm)

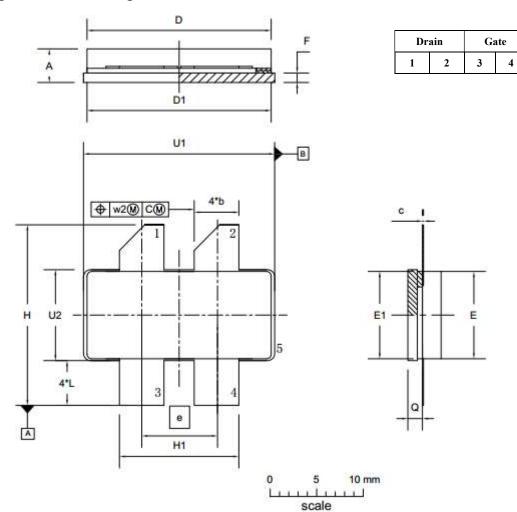




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#### Earless Flanged Ceramic Package; 4 leads



UNIT	A	b	С	D	D <sub>1</sub>	е	E	E <sub>1</sub>	F	Н	H1	L	Q	U <sub>1</sub>	U <sub>2</sub>	W <sub>1</sub>	W <sub>2</sub>
mm	4.72	4.67	0.15	20.02	19.96	7.00	9.50	9.53	1.14	19.94	12.98	5.33	1.70	20.70	9.91	0.25	0.51
mm	3.43	4.93	0.08	19.61	19.66	7.90	9.30	9.25	0.89	18.92	12.73	4.32	1.45	20.45	9.65	0.25	0.51
inahaa	0.186	0.194	0.006	0.788	0.786	0.244	0.374	0.375	0.045	0.785	0.511	0.210	0.067	0.815	0.390	0.01	0.00
inches	0.135	0.184	0.003	0.772	0.774	0.311	0.366	0.364	0.035	0.745	0.501	0.170	0.057	0.805	0.380	0.01	0.02

OUTLINE		REFERENCE		EUROPEAN	ISSUE DATE
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PKG-B4					03/12/2013

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#### **Revision history**

**Table 4. Document revision history** 

Date	Revision	Datasheet Status
2021/12/29	V1.0	Product Datasheet Creation
2022/3/21	V1.1	Modify typo from B4 to BY4
2022/6/26	V1.2	Correct BY4 back to B4
2023/10/22	V1.3	Modify the carrier application to new one with performance updated

Application data based on: JF-22-01/TC-22-13

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